

## MICROELECTRONIC DEVICES AND METHODS OF MANUFACTURE

### ABSTRACT

Supports (40) of microelectronic devices (10) are provided with underfill apertures (60) which facilitate filling underfill gaps (70) with underfill material (74). The underfill aperture may have a longer first dimension (62) and a shorter second dimension (64). In some embodiments, a method of filling the underfill gap (70) employs a removable stencil (80). If so desired, a stencil (80) can be used to fill multiple underfill gaps through multiple underfill apertures in a single pass.

Figure 11